

CG7 Series









Agency Approvals

AGENCY	AGENCY FILE NUMBER			
71	E128662			
71 2	E320116			

Two Electrode GDT Graphical Symbol



Additional Information







Samples

Description

The Littelfuse CG7 series GDT is a miniature surface mount device with a 1kA 8/20µS surge rating. Its low insertion loss and thus low offstate capacitance makes it compatible with high bandwidth applications up to the GHz RF range. This GDT's crowbarring characteristic protects sensitive ICs from surges as defined in ITU K.20/21/45 Basic and Enhanced Recommendations, GR-1089-CORE first level lightning Port Type 1 and 3, and IEC 61000-4-5 2nd edition. It is hermetically sealed using non-radioactive materials Classes 1-3 and some Class 4 & 5 cases and is thus environmentally safe. Its 2.8mm diameter size makes it the world's smallest two-electrode single chamber GDT available.

Features

- RoHS compliant and Lead-free
- Excellent Surge
 Withstanding Capability
- Excellent response to fast rising transients.
- Ultra Low Insertion Loss and low off-state capacitance for GHz bandwidth compatibility
- Ultra small devices offered in SMD package

- 1kA 8/20µS surge capability pulse as defined by IEC 61000-4-5 2nd edition
- Ultra Low capacitance (<0.3pF)
- Voltage Range 75V to 470V
- UL recognized

Applications

- Set top box
- Cable Modem
- Embedded Multimedia Terminal Adapter (EMTA)
- RF Connector
- Multimedia over Coax Alliance (MoCA)
- Base Station RF antenna transmitter
- G.Fast 106MHz and 212 MHz bandplans compatible
- CATV/Broadband equipment

- Data lines and Ethernet (up to 10GbE)
- Telecom line protection
- Broadband equipment
- xDSL equipment, including ADSL2, ADSL, VDSL, VDSL2 30a bandplan compatible
- IAD (Integrated Access Device)
- Aerospace and Automotive



Electrical Characteristics

	Device Specifications (at 25°C)						Life Ratings						
Part		Breakd in Volts @100V/s	S	Impulse Break- down in Volts (@100V/µs)	Impulse Break- down In Volts (@1kV/µs)	Insulation Resistance	Capaci- tance (@1MHz)	Max Impulse Discharge Current (8/20µs)	Max Impulse Discharge Current (10/700µs)	AC Dischage Current (9 cycle @50Hz)	DC Holdover Voltage (<150ms)	Impulse Life (8/20µs) (100A)	
Number	MIN	TYP	MAX	MAX		MIN	MAX			MIN		MIN	
CG775	60	75	90	600	700	1GΩ@50V	@50V		@1kA) 1 10 Shots	1A	52V		
CG790	72	90	108	600	700	10776201					52V		
CG7120	96	120	144	600	700			10 Shots (@1kA) 1			80V		
CG7150	120	150	180	600	700						80V		
CG7200	160	200	240	600	700	1GΩ@100V	0.0-4				135V	300 Shots	
CG7230	186	230	276	600	700		GΩ@100V 0.3pf	1 Shot			135V		
CG7250	200	250	300	600	700				at 2kA			135V	
CG7350	280	350	420	750	900							135V]
CG7400	360	400	480	850	1000						135V		
CG7470	376	470	564	900	1100	1GΩ@250V					135V		

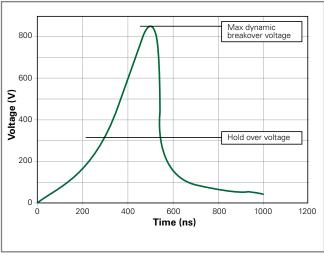
Notes:

- UL Pending for CG775 and CG7470.
- 1. $5 \times (+)$ and $5 \times (-)$ applications of 1kA 8/20 μ s sec.
- 2. $5 \times (+)$ and $5 \times (-)$ applications of 100A 10/700 μ s sec.

Product Characteristics

Materials	Device Tin Plated 17.5 ± 12.5 Microns Construction: Ceramic Insulator		
Storage and Operational Temperature	-40 to +90°C		

Voltage Vs. Time Characteristic



Note: Tested per 1kV/µs waveform

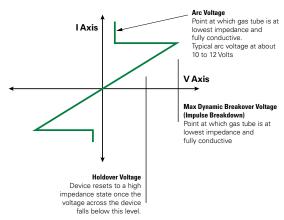
Typical Insertion Loss

@1.0GHz = 0.02dB
@1.4GHz = 0.03dB
@1.8GHz = 0.05dB
@2.0GHz = 0.06dB
@2.4GHz = 0.07dB
@2.8GHz = 0.08dB
@3.1GHz = 0.09dB
@3.5GHz = 0.10dB
@4.0GHz = 0.12dB
<u> </u>

Note: Insertion data for customer reference only, application testing needed for verification.

V-I Characteristic Curve

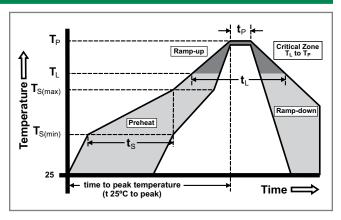
Characteristics of Gas Plasma -response to transient condition





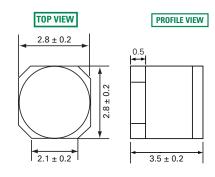
Soldering Parameters - Reflow Soldering (Surface Mount Devices)

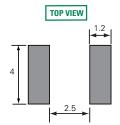
Reflow Co	ndition	Pb – Free assembly		
	-Temperature Min (T _{s(min)})	150°C		
Pre Heat	-Temperature Max (T _{s(max)})	200°C		
	-Time (Min to Max) (t _s)	60 – 180 secs		
Average ra	amp up rate (LiquidusTemp k	3°C/second max		
T _{S(max)} to T _L	- Ramp-up Rate	5°C/second max		
Reflow	-Temperature (T _L) (Liquidus)	217°C		
nellow	-Temperature (t _L)	60 – 150 seconds		
PeakTemp	perature (T _P)	260+ ^{0/-5} °C		
Time with Temperate	in 5°C of actual peak ure (t _p)	10 – 30 seconds		
Ramp-dov	vn Rate	6°C/second max		
Time 25°C	to peakTemperature (T _P)	8 minutes Max.		
Do not exc	ceed	260°C		



Device Dimensions

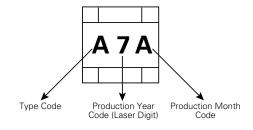
Dimensions in millimeters





Recommended Soldering Pad Layout

Product Marking



Type Code					
Α	CG775				
В	CG790				
Т	CG7120				
С	CG7150				
0	CG7200				
D	CG7230				
R	CG7250				
G	CG7350				
ı	CG7400				
P	CG7470				

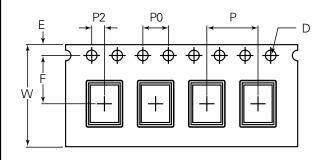
Month Code						
Α	January					
В	February					
С	March					
D	April					
E	May					
F	June					
G	July					
Н	August					
ı	September					
J	October					
K	November					
L	December					



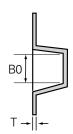
Taping and Reel Specifications

Unit = mm

Item	Spec		ltem	Spec
Р	8.0 ± 0.1		Е	1.75 ± 0.1
P0	4.0 ± 0.1		D	1.50 + 0.1/-0.0
P2	2.0 ± 0.1		В0	3.9 ± 0.1
W	12.0 ± 0.3		K0	3.2 ± 0.1
F	5.5 ± 0.1		Т	0.4 ± 0.1
A0	3.2 ± 0.1		10P0	4.0 ± 0.2

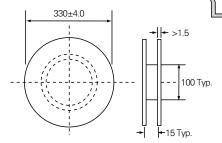


K0

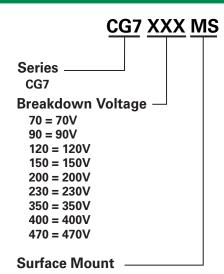


Packaging Quantity:

2500 pcs per reel (13") 1 reels per inner box 10 inners box per carton 25,000 pcs per full carton



Part Numbering System and Ordering Information



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